

# Low interface states and high dielectric constant $Y_2O_3$ films on Si substrates

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$Y_2O_3$  films were deposited on *c*-Si substrates at temperatures in the 400–550 °C range, with no further thermal treatment given to these samples, using the spray pyrolysis technique. The spraying solution was yttrium acetylacetonate dissolved in *N,N*-dimethylformamide. In addition, a solution of  $H_2O-NH_4OH$  was sprayed in parallel during the deposition process to improve the optical, structural, and electrical properties of the deposited films. The growth of a  $SiO_2$  layer between the yttrium oxide and the Si substrate during this deposition process resulted in interface state density values as low as  $10^{10} eV^{-1} cm^{-2}$ . An effective refractive index value of 1.86, and deposition rates close to 1 Å/s were obtained. The  $Y_2O_3$  films were polycrystalline with a crystalline cubic phase highly textured with the (400) direction normal to the Si surface. An effective dielectric constant up to 13, as well as a dielectric strength of the order of 0.2 MV/cm was obtained for  $\sim 1000$  Å thick as-deposited films incorporated in a metal-oxide-semiconductor structure. © 2006 American Vacuum Society. [DOI: 10.1116/1.2214710]

## I. INTRODUCTION

High- $\kappa$  dielectric thin films are being studied for a variety of applications. Several materials have been studied for this purpose. In particular, metal oxides such as  $ZrO_2$ ,  $HfO_2$ ,  $Al_2O_3$ , as well as rare-earth oxides such as  $Y_2O_3$ ,  $La_2O_3$ ,  $Pr_2O_3$ , and  $Gd_2O_3$  have been proposed to replace  $SiO_2$  because their high dielectric constant ( $10 < \kappa < 30$ ), thermal stability, a relatively high conduction band offset, and a high dielectric breakdown.<sup>1</sup> Yttrium oxide ( $Y_2O_3$ ) has a dielectric constant between 14 and 18,<sup>2</sup> a high crystalline stability<sup>3</sup> and mechanical strength,<sup>4</sup> and a high refractive index ( $n \approx 2$ ).<sup>5</sup> Epitaxial growth of rare-earth oxides has been reported to be achieved using molecular beam epitaxy (MBE).<sup>6</sup> Several other deposition methods have been used to obtain  $Y_2O_3$  thin films, such as pulsed laser deposition,<sup>7</sup> rf-magnetron sputtering,<sup>8</sup> spray pyrolysis,<sup>9</sup> and sol gel.<sup>10</sup> In the present work we report the deposition and characterization of  $Y_2O_3$  thin films obtained by ultrasonic spray pyrolysis. These films were deposited from a spraying solution of yttrium acetylacetonate [ $Y(acac)_3$ ] in *N,N*-dimethylformamide (*N,N*-DMF). The mist of a second spraying solution, consisting of a mixture of  $H_2O-NH_4OH$ , supplied simultaneously, and in parallel to the yttrium spraying solution, improved dramatically

the optical, structural, and dielectric properties of the  $Y_2O_3$  films. Specifically, the formation of a high quality interfacial layer of  $SiO_2$  improved the interface characteristics with the silicon substrate.

## II. EXPERIMENTAL PROCEDURE

The ultrasonic spray pyrolysis technique was used to deposit the  $Y_2O_3$  films on *c*-Si wafers with (100) orientation and low resistivity or (111) and high resistivity, for electrical and optical measurements, respectively. The silicon wafers were previously cleaned with a well established procedure.<sup>11</sup> Spray pyrolysis is considered a simple and low cost deposition method for film deposition. This technique has been used to obtain high quality metallic oxides.<sup>12–15</sup> It consists of an ultrasonic generator used for mist production from a spraying solution containing the proper reactive materials. The mist is transported through a glass tube to the substrate surface which is being heated to achieve a pyrolytic chemical reaction. This deposition process is performed in an atmospheric pressure air ambient. In this work, a 0.03 M yttrium spraying solution was prepared by dissolving  $Y(acac)_3$  in *N,N*-DMF, from Alfa AESAR and J.T. Baker, respectively. In addition, the mist of a second spraying solution, consisting of a mixture of  $1H_2O-1NH_4OH$  (J.T. Baker), was also carried, during the deposition process, to the surface of the silicon wafers, used as substrates. The mists of both spraying

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